

TVS Diodes

Transient Voltage Suppression Diodes

SPC1 Series



Description

The SPC1 in SMT0-218 package provide the enhanced quality, easy manufacturing than typical through-hole TVS components. They can be connected in series and/or parallel to create various capability and flexible protection solutions.

Applications

- Communication Equipment
- Security & Protection
- Industrial Control Equipment
- Power Supply
- Automotive Electronics
- New Energy
- Lightning Protection

Features

- Bi-directional
- Low clamping and slope resistance
- For automatic pick and place assembly and reflow process to reduce the manufacturing cost and increase the soldering quality compared to axial leads package
- Patent pending package design
- Meet MSL level 1, per J-STD-020, LF Maximum peak of 245 °C
- Pb-free E3 means 2nd level interconnect is Pb-free and the terminal finish material is tin (Sn)
- ESD follow IEC 61000-4-2
- Halogen free and RoHS compliant
- Tube or tape and reel pack options available

Functional Diagram

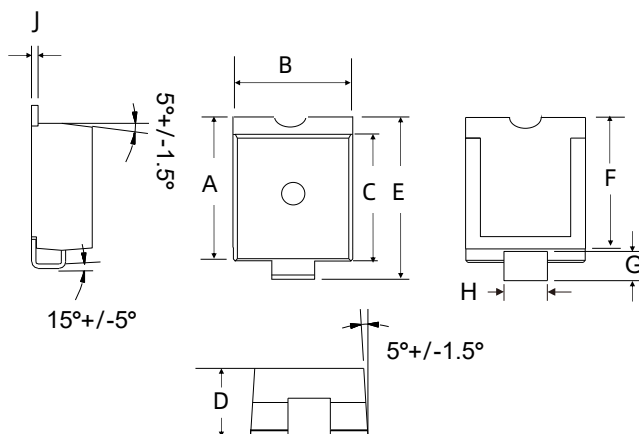


Bi-Directional

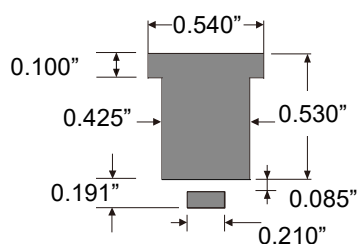
Electrical Characteristics (T_A=25 °C unless otherwise noted)

Part Number	Stand-off Voltage V _R	Max. Reverse Leakage I _R @V _R	Breakdown Voltage V _{BR} @I _T		Test Current I _T	Max. Clamping Voltage V _{CL} @Peak Pulse Current (I _{PP})			Max. Temp Coefficient of V _{BR}	Max. Capacitance 0 Bias 10KHz
			Min	Max		V _{CL}	I _{PP} (8/20 μS)	I _{PP} (10/350 μS)		
							Min	Typical		
		(V)	(μA)	(V)		(uA)	(V)	(A)	(A)	(%/°C)
SPC1-380C	380	10	401	443	10	520	1000	100	0.1	2.2
SPC1-430C	430	10	440	490	10	625	1000	100	0.1	2.2

Package Outline Dimensions (SMT0-218)



Note: Coplanarity of solder side is controlled within 0.10mm



Mounting Pad Layout (Inch)

Symbol	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	15.78	16.63	0.621	0.655
B	13.43	15.09	0.529	0.594
C	13.83	14.24	0.544	0.561
D	6.94	7.24	0.273	0.285
E	17.82	18.72	0.702	0.737
F	14.40	14.76	0.567	0.581
G	1.88	2.84	0.074	0.112
H	4.89	5.65	0.193	0.222
J	0.72	0.85	0.028	0.033

Maximum Ratings and Characteristics

(Ratings at 25 °C ambient temperature unless otherwise specified.)

Parameter	Symbol	Value	Unit
Storage Temperature Range	T _{STG}	-55 to 150	°C
Operating Junction	T _J	-55 to 125	°C
Current Rating (8/20 μS wave)	I _{PP}	10	kA

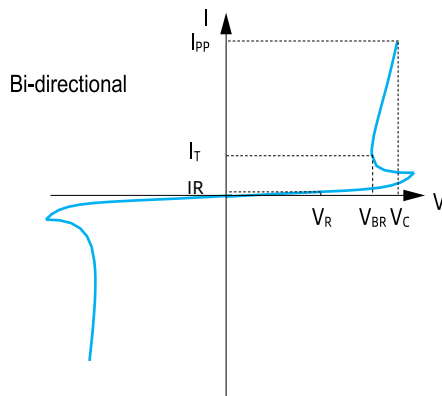
Physical Specifications

Weight	Contact manufacturer
Case	Epoxy molding compound encapsulated
Terminal	Tin plated lead, solderability per MIL-STD-202 Method 208

Environmental Specifications

Temperature Cycling	JESD22-A104
HTRB	JESD22-A108
MSL	JESDEC-J-STD-020, Level 1
H3TRB	JESD22-A101
RSH	JESD22-B106

I-V Curve Characteristics



P_{PPM} - Peak Pulse Power Dissipation

V_R - Stand-off Voltage

V_{BR} - Breakdown Voltage

V_C - Clamping Voltage

I_R - Reverse Leakage Current

Performance Curve for Reference ($T_A=25^\circ\text{C}$ unless otherwise noted)

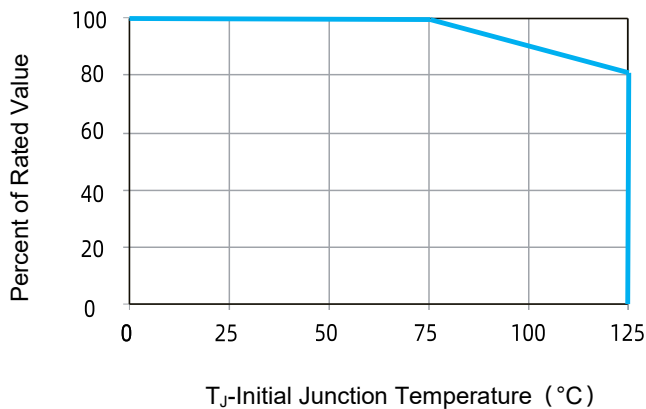


FIGURE 1 Peak Power Derating

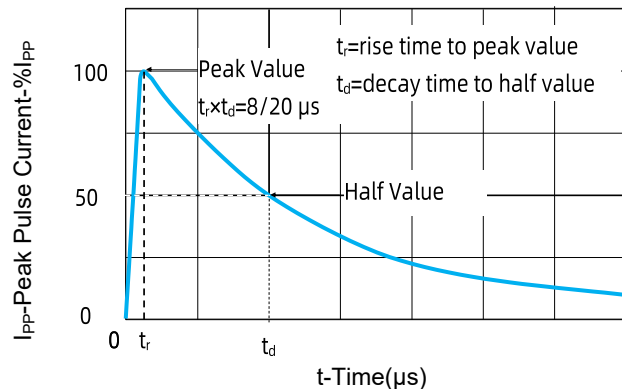
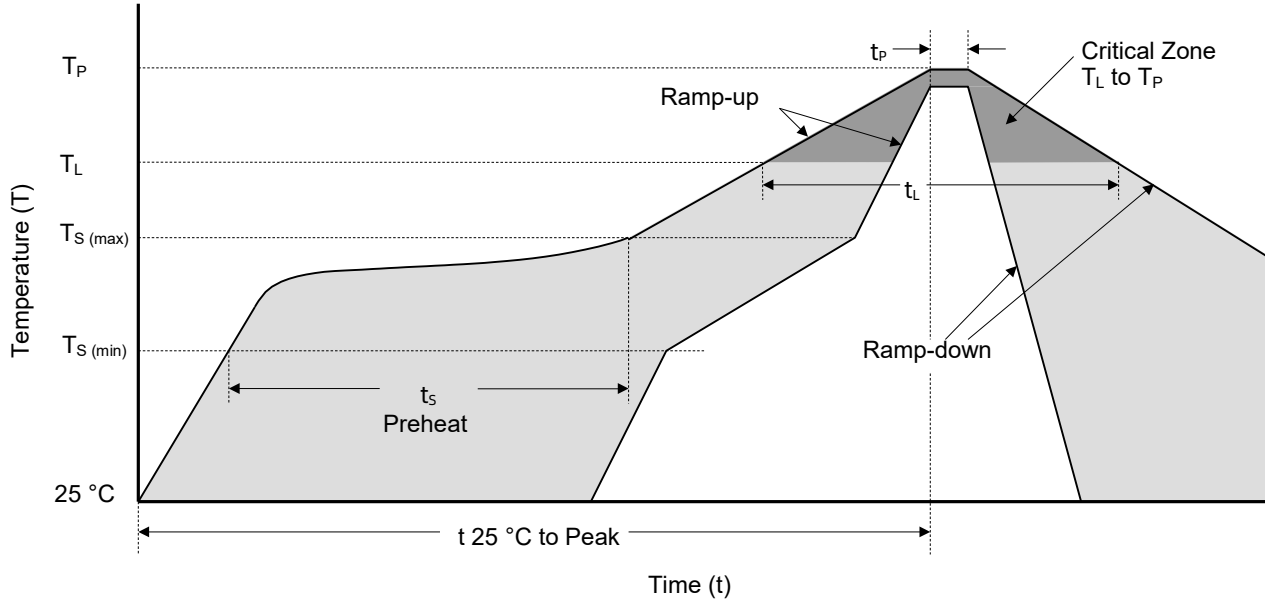


FIGURE 2 Pulse Waveform

Soldering Parameters



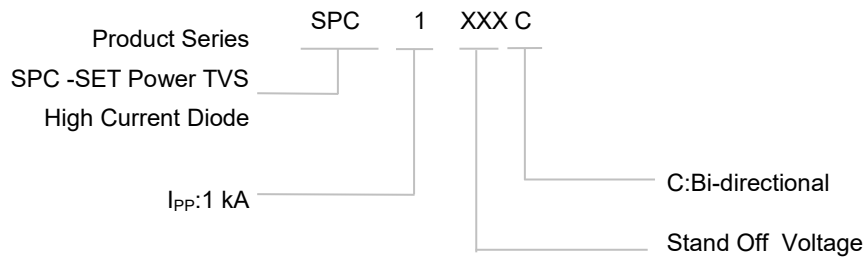
Reflowing Condition

Reflow Soldering Parameters		Lead-Free Assembly
Pre-heat	Temperature Min (T _{S (min)})	150 °C
	Temperature Max (T _{S (max)})	200 °C
	Time (min to max) (t _s)	60 ~ 120 seconds
Average Ramp Up Rate (Liquidus Temp (T _L) to Peak)		3 °C / second max.
T _{S (max)} to T _L Ramp-up Rate		3 °C / second max.
Reflow	Temperature (T _L) (Liquidus)	217 °C
	Time (min to max) (t _L)	60 ~ 150 seconds
Peak Temperature (T _P)		260 ^{+0/-5} °C
Time of within 5 °C of Actual Peak Temperature (t _p)		20 ~ 40 seconds
Ramp-down Rate		6 °C / second max.
Time from 25 °C to Peak Temperature		8 Minutes max.
Do Not Exceed		260 °C

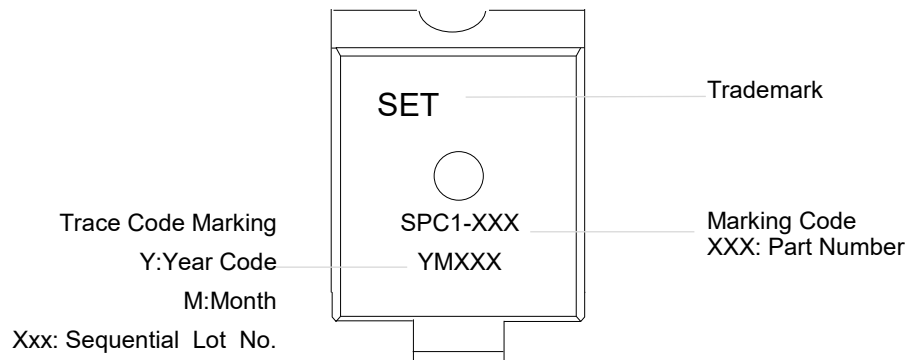
Wave Soldering (Solder Dipping)

Peak Temperature	260 °C+0 /- 5 °C
Dipping Time	10 seconds
Soldering Number	1 time

Part Numbering System



Marking



Packaging Information

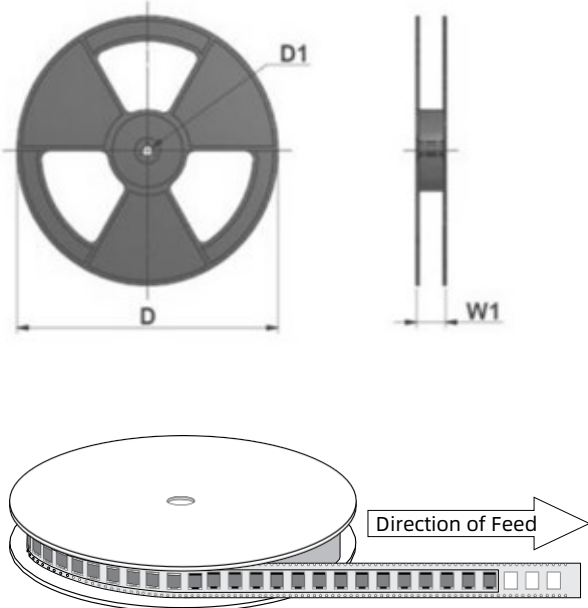
Tape		Symbol	Millimeters	Inches
		W	32±0.3	1.260±0.012
		E	1.75±0.1	0.069±0.004
		F	14.2±0.1	0.559±0.004
		D ₀	1.5±0.1/0.0	0.059±0.004/-0.0
		P ₀	4.0±0.1	0.102±0.004
		P ₁	20.0±0.1	0.787±0.004
		P ₂	2.0±0.1	0.079±0.004
		A ₀	14.5±0.1	0.571±0.004
		B ₀	18.5±0.1	0.728±0.004
		T	0.40	0.016
		T ₁	7.8	0.029

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SPC1 Series

Packaging Information

	Symbol	Millimeters	Inches
	D	Φ13.0	Φ330.0
	D ₁	Φ0.520±0.008	Φ13.2±0.2
	W ₁	1.417±0.079	36.0±2.0

Part Number	Weight	Packaging Option	QTY' s
SPC1-XXXXC	4.33 g	Tape & Reel – 32 mm/13" tape	400 PCS

Glossary

Item	Description
V_C	Clamping Voltage Voltage across TVS in a region of low differential resistance that serves to limit the voltage across the device terminals.
V_{WM} (V_R) (V_{SO})	Rated Working Standoff Voltage Maximum-rated value of dc or repetitive peak positive cathode-to-anode voltage that may be continuously applied to TVS over the standard operating temperature range.
I_D (I_R)	Standby Current Current through TVS at rated stand-off voltage.
V_{BR}	Breakdown Voltage Voltage across TVS at a specified current I _T in the breakdown region.
I_{PPM}	Rated Random Recurring Peak Impulse Current Maximum-rated value of random recurring peak impulse current that may be applied to a device.
P_{M(AV)}	Rated Average Power Dissipation Maximum-rated value of power dissipation resulting from all sources, including transients and standby current, averaged over a short period of time.
P_{PPM}	Rated Random Recurring Peak Impulse Power Dissipation Maximum-rated value of the product of rated random recurring peak impulse current (I _{PPM}) multiplies by specified maximum clamping voltage (V _C).
C_J	Capacitance Capacitance across the TVS measured at a specified frequency and voltage.
V_{FS} (V_F)	Peak Forward Surge Voltage Peak voltage across an TVS for a specified forward surge current (I _{FS}) and time duration.
I_{FS} (I_F)	Forward Surge Current Pulsed current through TVS in the forward conducting region.
α_{V(BR)}	Temperature Coefficient of Breakdown Voltage The change of breakdown voltage divided by the change of temperature.
I_{PP}	Peak pulse Current Peak pulse current value applied across the TVS to determine the clamping voltage V _C for a specified wave shape.

—(GB-T 18802.321 / IEC 61643-321 / JESD210A)



ATTENTION

Usage

1. TVS must be operated in the specified ambient temp.
2. Do not clean the TVS with strong polar solvent such as ketone, esters, benzene and halogenated hydrocarbon, to avoid damaging the encapsulating layer.
3. Please do not apply severe vibration, shock or pressure to TVS, to avoid element cracking.

Replacement

1. If TVS is visually damaged, please replace it.
2. TVS is a non-repairable product. For safety sake, please use equivalent TVS for replacement.

Storage

1. Storage Temp. Range: (-55 to 150) °C.
2. Do not store the TVS at the high temp., high humidity or corrosive gas environment, to avoid influencing the solderability of the lead wires. The product shall be used up within 1 year after receiving the goods.

Environmental Conditions

1. TVS should not be exposed to the open air, nor direct sunshine.
2. TVS should avoid rain, water vapor or other condition of high temp. and high humidity.
3. TVS should avoid sand dust, salt mist, or other harmful gases.

Max. Typical Capacitance of TVS

The typical capacitance of TVS is listed in the specifications. Designers may refer to it when designing TVS in High frequency circuit.

Installation Mechanical Stress

1. Do not knock TVS when installing, to avoid mechanical damage.
2. Please do not apply severe vibration, shock or pressure to TVS, to avoid surface resin or element cracking.